

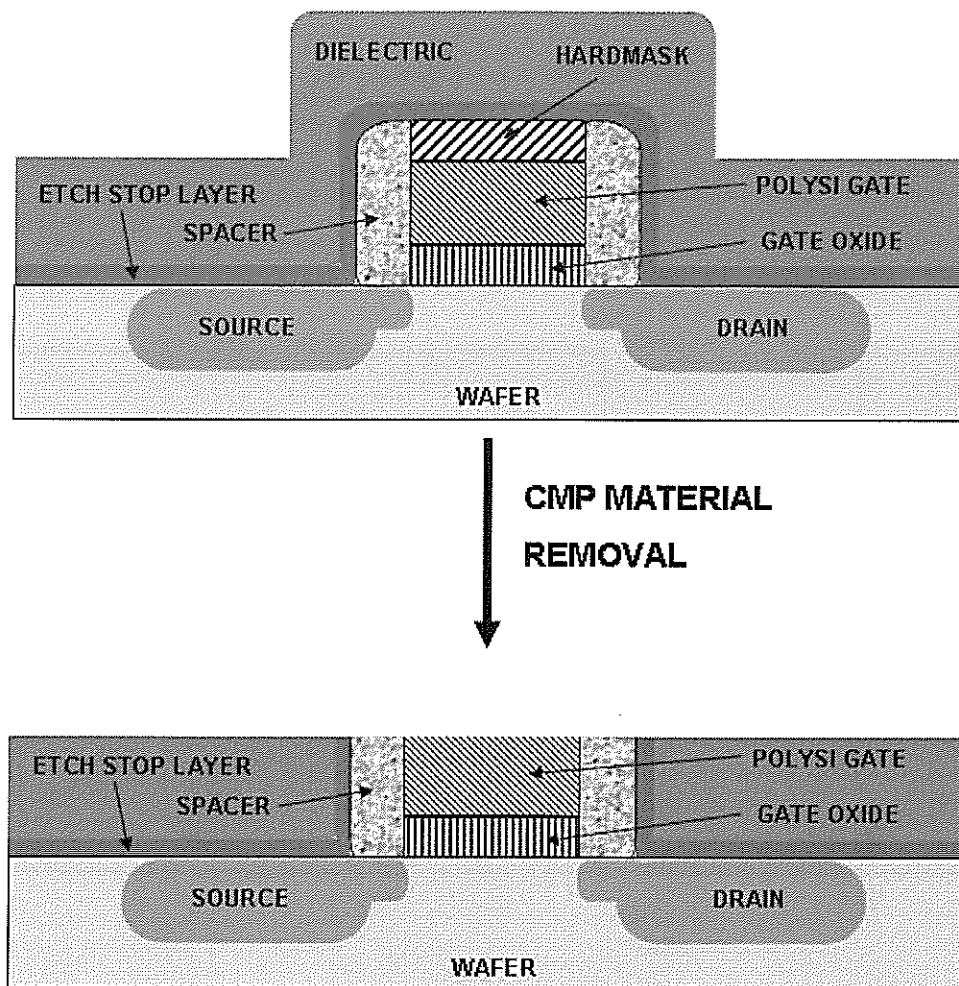


Fig 1
Material Removal in Poly-Open Polish Process.

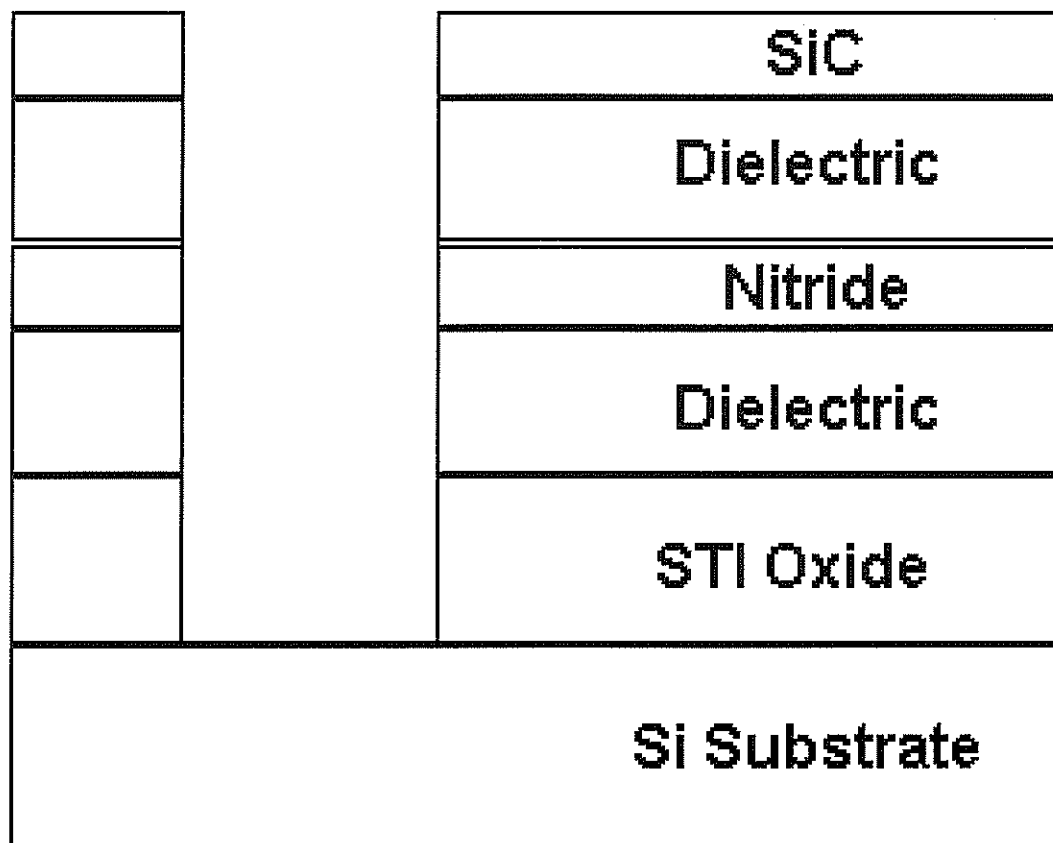


Fig 2
3D System Level Thorough-Silicon-Vias Integration Scheme

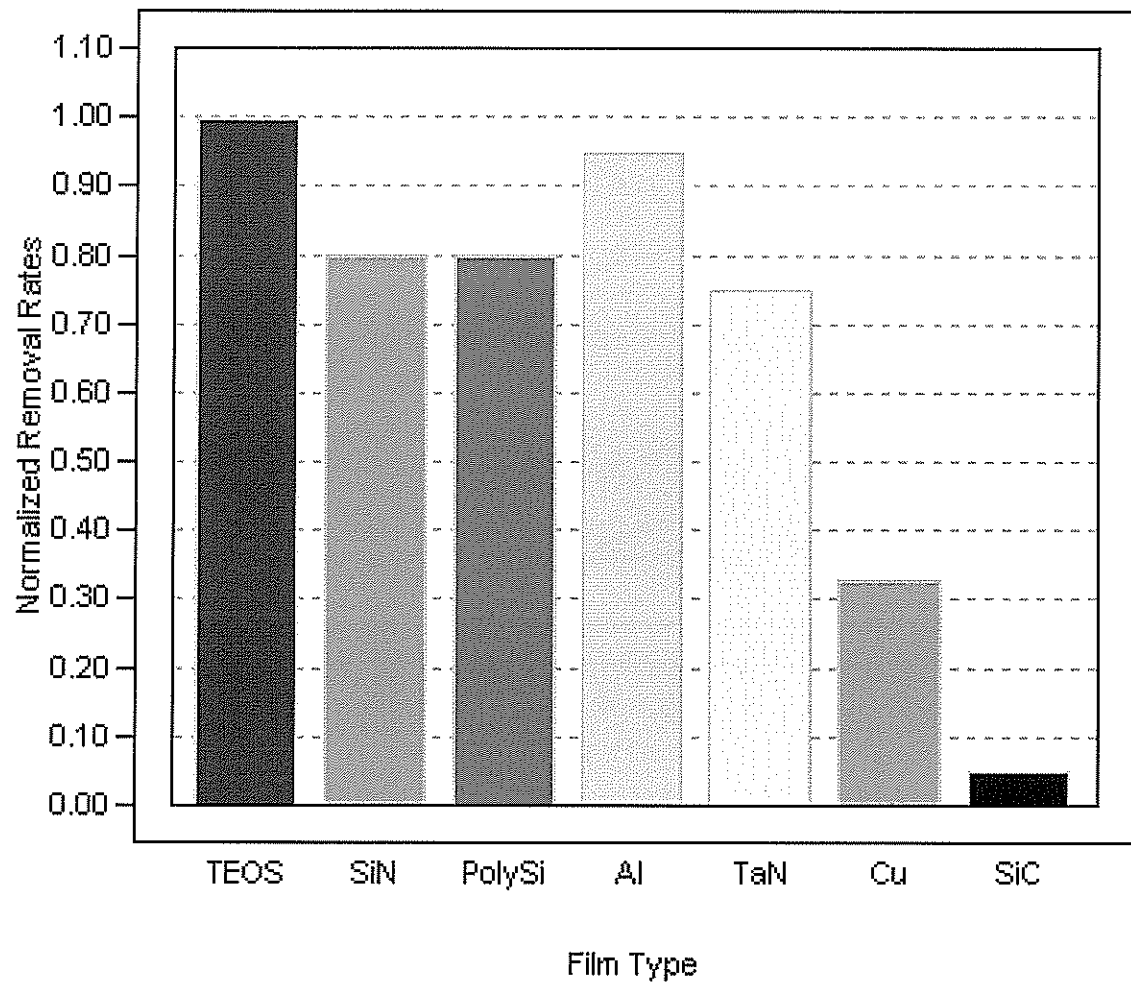


Fig 3
Typical Normalized Removal Rates for Various Substrates.

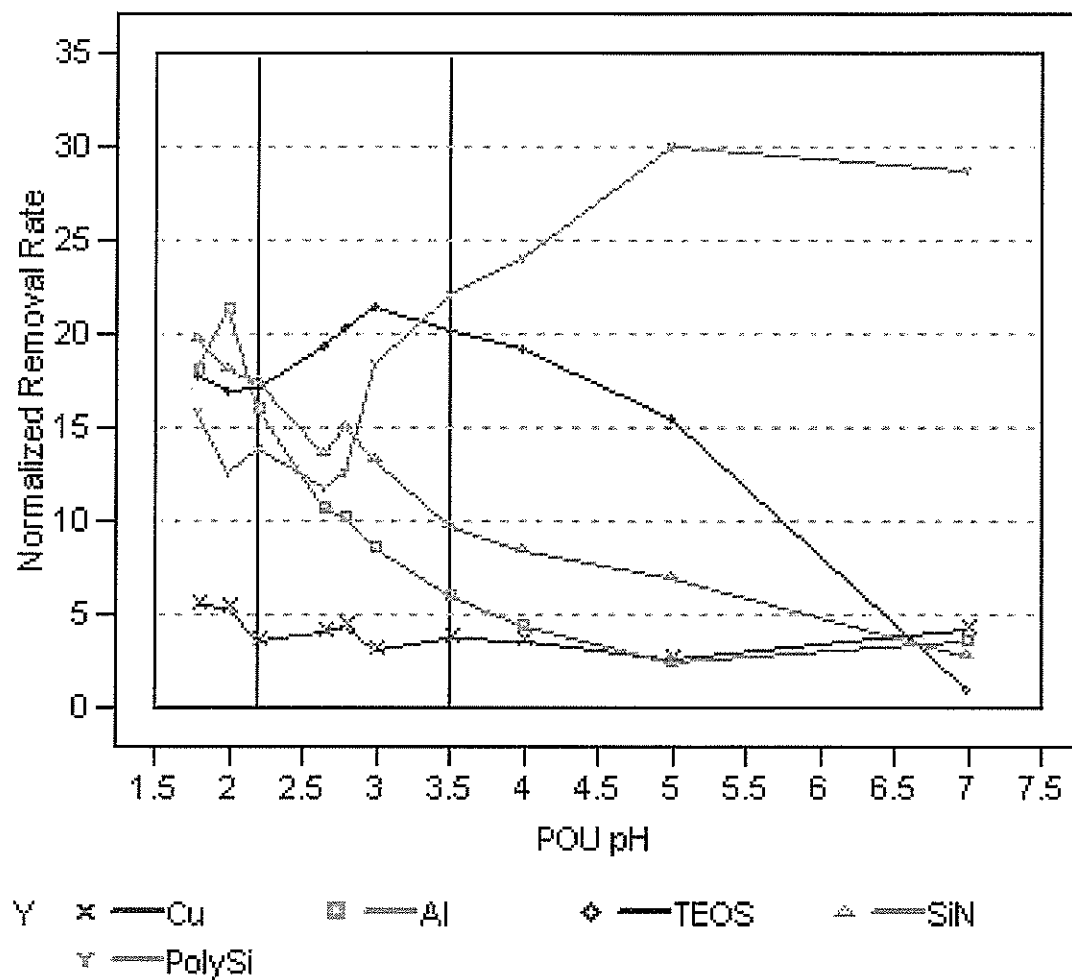


Fig 4
Typical Normalized Removal Rates by Film Type vs. POU pH

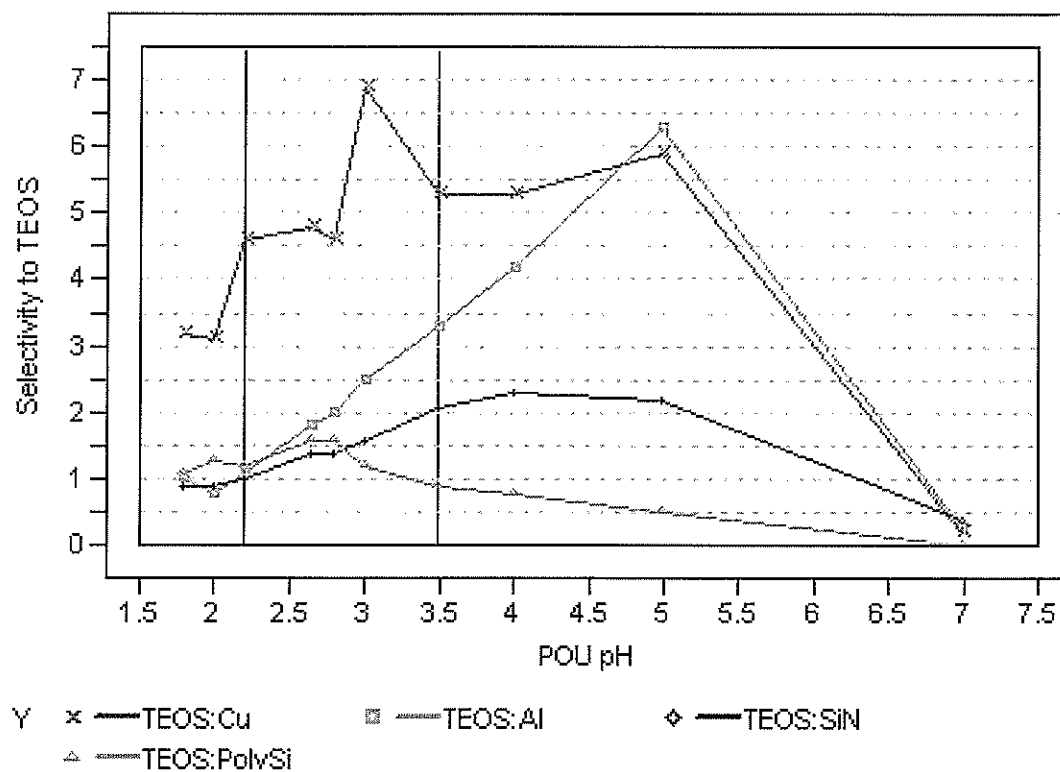


Fig 5
Typical TEOS:Film Selectivity

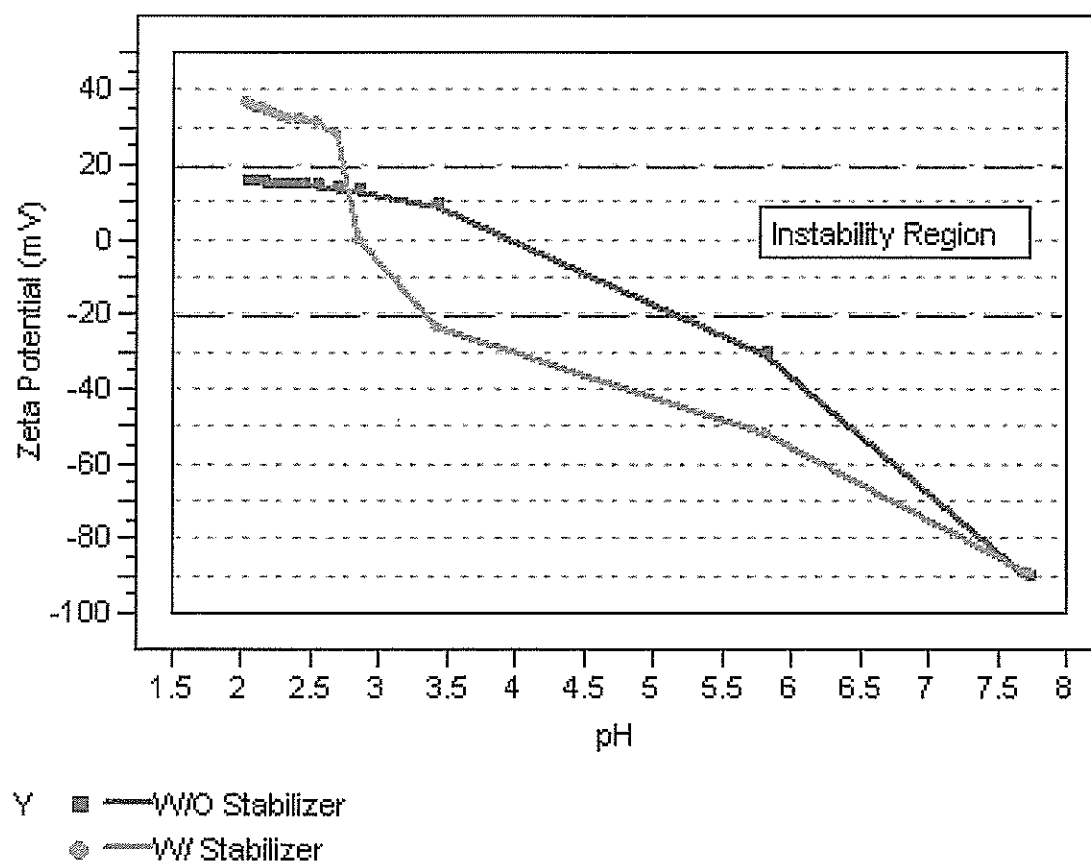


Fig 6
Zeta Potential vs. pH for Concentrate

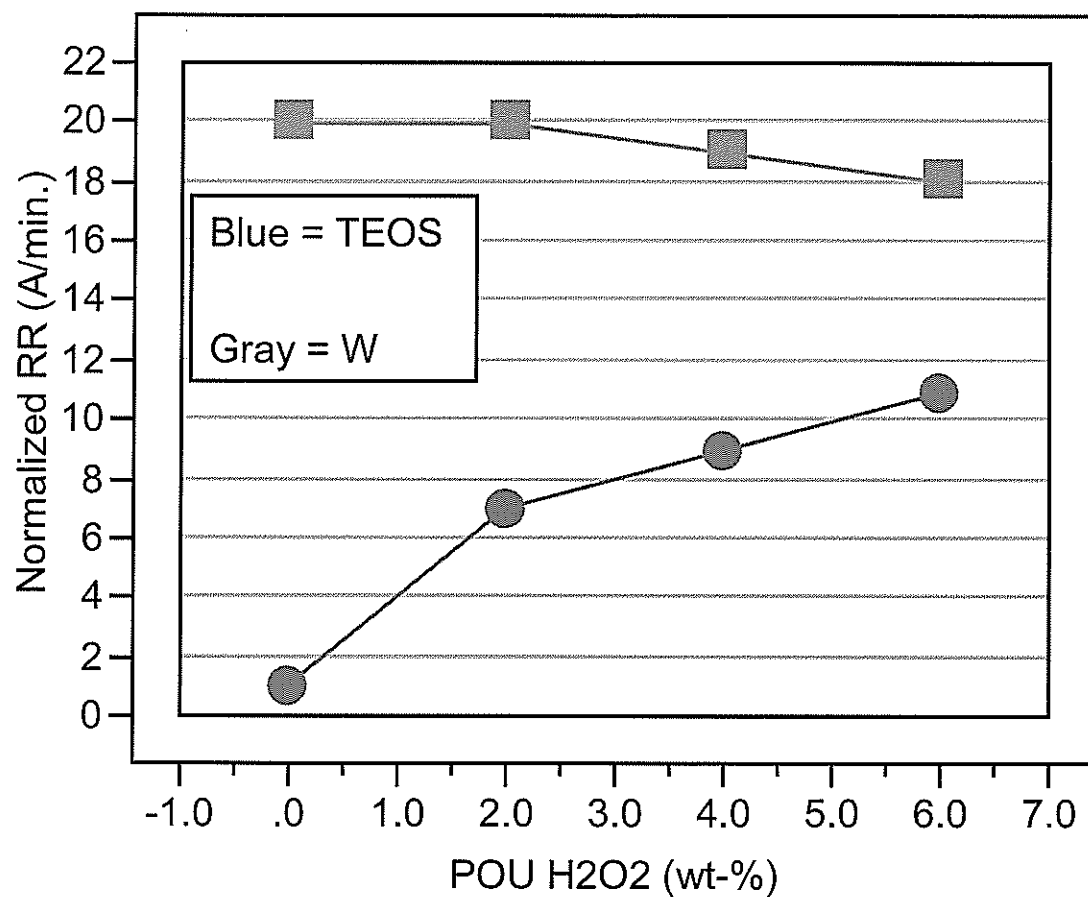


Fig. 7
Normalized TEOS and Tungsten (W) Removal Rates vs. POU
Hydrogen Peroxide Concentration